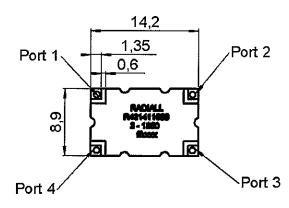
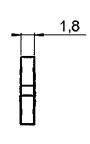
1.7 -2.0 GHZ

R431.411.002

Series : COUPLEUR



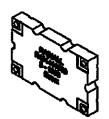


RF Port configuration

|      | Input | Isol. | -90° | 0 |  |
|------|-------|-------|------|---|--|
| Port | 1     | 2     | 3    | 4 |  |
|      | 2     | 1     | 4    | 3 |  |
|      | 3     | 4     | 1    | 2 |  |
|      | 4     | 3     | 2    | 1 |  |



Scale 1:1



All dimensions are in mm.



Issue: 0450 C



#### TECHNICAL DATA SHEET

# **SMT HYBRID COUPLER**

1.7 -2.0 GHZ

R431.411.002

Series : **COUPLEUR** 

#### **ELECTRICAL CHARACTERISTICS**

|                           |   | Specified balld | Extended ban |
|---------------------------|---|-----------------|--------------|
| Frequency (GHz)           |   | 1.7 - 2.0       | 1.5 - 2.2    |
| V.S.W.R                   | ≤ | 1.18            | 1.2          |
| Impedance $(\Omega)$      |   | 50              |              |
| Nominal coupling (dB)     |   | 3               | 3            |
| Amplitude balance (dB)    | ± | 0.3             | 0.4          |
| Phase balance: 90 (°)     | ± | 3               | 3            |
| Isolation (dB)            | ≥ | 23              | 20           |
| Insertion loss (dB)       | ≤ | 0.23            | 0.23         |
| Average power at 25°C (W) |   | 100             | 100          |

# **MECHANICAL CHARACTERISTICS**

Mounting RF Port finish Weight Surface Mount Technology
Chemical Sn
1.000 g

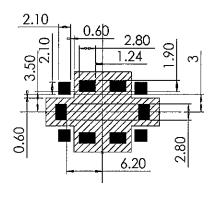
# **ENVIRONMENTAL**

Operating temperature range Storage temperature range

-55 / +85 -55 / +85 °C

SPECIFICATION

# **SOLDERING PATTERN**



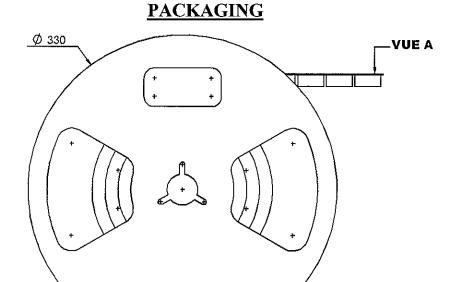
Issue: 0450 C

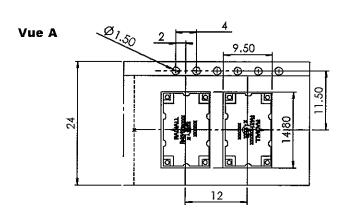


1.7 -2.0 GHZ

R431.411.002

Series: COUPLEUR





Issue: 0450 C



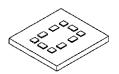
1.7 -2.0 GHZ

R431.411.002

Series: COUPLEUR

#### **SOLDERING GUIDELINES**

(1) Solder cream deposition:



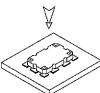
RADIALL recommends using a solder cream Sn96.5 - Ag3 - Cu0.5 type "no clean - low residue" (50% solid residue of flux quantity) that will permit the elimination of the cleaning operation step after soldering. When using a conventional solder cream with high level of flux solid residue, it is important to incorporate a good cleaning operation step in the fifteen minutes after soldering.

The substrate must have chemical Sn protection. Please optically verify that the edges of the zones are clean, without contaminates and that the PCB zoned areas have not oxydated.

Solder cream may be applied on the board with screen printing or dispenser techniques. For either method, the paste solder must be coated to appropriate thickness and shapes to achieve good solder wetting and adequate insulation.

The design of the mounting pads and the stencilling area are given in the applicable note, for a thickness of the silk-screen printing of 150 µm.

2) Placement of the coupler:



For small , lightweight components such as chip components , a self-alignment effect can be expected if small placement errors exist. However, this effect is not as expected for couplers components and they require precise positioning on their soldering pads; typically  $\pm$  0.25 mm.

Place the coupler onto the PCB with automatic pick and place equipment. Various types of suction can be used.

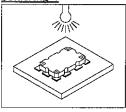
RADIALL does not recommend using adhesive agents on the component or on the  $\ensuremath{\text{PCB}}$  .

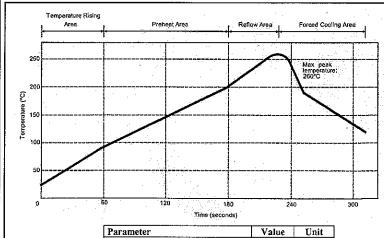
Please follow RADIALL's recommended temperature profile.

This profile can be used with Infra red reflow. Vapor phase of

This profile can be used with Infra - red reflow, Vapor phase soldering and Forced air convection.

3 Soldering:





| Parameter                        | Value    | Unit   |
|----------------------------------|----------|--------|
| Temperature rising Area          | 1 - 4    | °C/sec |
| Max Peak Temperature             | 260      | °C     |
| Max dwell time @260°C            | 10       | sec    |
| Min dwell time @235°C            | 20       | sec    |
| Max dwell time @235°C            | 60       | sec    |
| Temperature drop in cooling Area | -1 to -4 | °C/sec |
| Max dwell time above 100°C       | 420      | sec    |

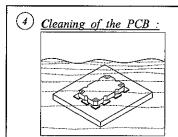
Issue: 0450 C



1.7 -2.0 GHZ

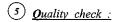
R431.411.002

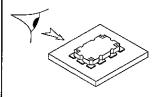
Series: COUPLEUR



When using a conventional solder cream with high level of residue, please clean the PCB with a substitute product, similar to CFC, that complies to the International Environment Agency rules. It is important to do the cleaning operation step less than fifteen minutes after reflow.

RADIALL recommends using ultrasonic waves or vapor phase process.





Verify by visual inspection that component is centred on the mounting pads. Solder joints: verify by visual inspection that the formation of meniscus on the pads are proper, and have a capilarity amount upper the third of the height.

Issue: 0450 C

